

# **PRODUCT CHANGE NOTICE**

**Product Improvement – Wafer Backside  
Material and Die Attach Process Change  
for Intersil EL1848\*, EL7513\* and  
EL7518\* Products**

**Refer to:  
PCN04042**

**Date: August 20, 2004**

August 20, 2004

To: Our Valued Intersil Customers

Subject: **Product Improvement – Wafer Backside Material and Die Attach Process Change for Intersil EL1848\*, EL7513\* and EL7518\* Products**

Intersil's commitment to the concepts of total quality management, customer satisfaction, and continuous improvement is supported by a strategy of manufacturing changes to enhance quality and reliability. This notice is to inform you of a change in the wafer backside material and die attach process for the EL1848\*, EL7513\*, and EL7518\* series products. The qualification activity is in process.

These changes are intended to provide a more robust device and will not affect the form, fit, function, or interchangeability of product. The wafer backside material is changing from gold to bare silicon. The die attach method is changing to a multi layer process designed to increase its thickness during device assembly, with no change to the die attach material. There will be no change in the package external dimensions or moisture sensitivity level.

The qualification plan is designed using JEDEC and other applicable industry standards and is contained in Attachment A. Details of the qualification activity will be available upon completion by request. The remainder of the manufacturing operations (assembly, product electrical testing, shipment, etc.) will continue to be processed to established conditions and systems.

There will be no change in external marking of the packaged parts. Parts affected by this change are identifiable via Intersil's internal traceability system.

Intersil will take all necessary actions to conform to customer requirements ensuring the continued high quality and reliability of products being supplied. Customers may expect to receive product affected by this change beginning immediately.

If you have concerns with this change notice, Intersil must hear from you immediately. Please contact the nearest Intersil Sales Office or call the Intersil Corporate hot line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

*Jon Brewster*

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PCN04042

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## **Products Affected – PCN04042**

EL1848IWT  
EL1848IWT-T7  
EL1848IWT-T7A  
EL1848IWTZ  
EL1848IWTZ-T7  
EL1848IWTZ-T7A  
EL7513AIWT  
EL7513AIWT-T7  
EL7513AIWT-T7A  
EL7513AIWTZ  
EL7513AIWTZ-T7  
EL7513AIWTZ-T7A  
EL7513IWT  
EL7513IWT-EVAL  
EL7513IWT-T13  
EL7513IWT-T7  
EL7513IWT-T7A  
EL7513IWTZ  
EL7513IWTZ-T7  
EL7513IWTZ-T7A  
EL7518IWT  
EL7518IWT-T7  
EL7518IWT-T7A  
EL7518IWTZ  
EL7518IWTZ-T7  
EL7518IWTZ-T7A

## Appendix A – Package Qualification Plan – PCN04042

<b>Test</b>	<b>Conditions</b>	<b>Sample</b>
<b>Temp Cycle</b>	MIL-STD-883, Method 1010 -65°C/+150°C, 1000 cycles	76
<b>Temp/Humidity Bias HAST</b>	JEDEC JESD22-A110-B 130°C/85%RH with BIAS 96 hrs	45
<b>Pressure Pot or Unbiased HAST</b>	JEDEC Std-22-A102, 168 hrs. unbiased, 121°C, 100%RH at 2 atm  JEDEC JESD22-A110-B 130°C/85%RH without BIAS 168 hrs	45
<b>Moisture Sensitivity</b>	IPC/JEDEC J-STD-020B with IR Reflow at 260°C Std package	22
<b>High Temp Storage</b>	MIL-STD-883, Method 1008, 1000 hrs. unbiased bake at 150°C	22